

# TG4040S

## High Performance Thermal Interface Materials

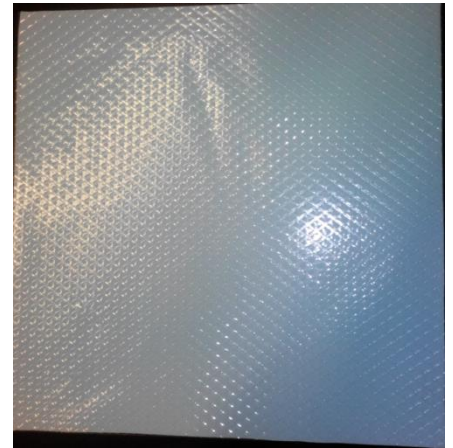


### Features

Low hardness  
Naturally tacky  
Low oil bleed

### Applications

Electronic components: IC / CPU / MOS  
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc....  
DDR II Module / DVD Applications / Hand-Set applications etc...



### Properties

Property	TG4040S	Unit	Test Method
Colour	Blue	-	Visual
Construction	Silicone Gel	-	-
Optimum Temp. Range	-45 to 200	°C	-
Density	2.6	g/cm <sup>3</sup>	ASTM D792
Thermal Conductivity	4.2	W/mK	ASTM D5470
Shore 00	20	-	ASTM D2250
t=1.0mm Thermal impedance @10psi	0.55	K-in <sup>2</sup> /W	ASTM D575
t=1.0mm Thermal impedance @50psi	0.41	K-in <sup>2</sup> /W	ASTM D575
t=1.0mm Thermal impedance @100psi	0.33	K-in <sup>2</sup> /W	ASTM D575
t=1.0mm Percent Deflection % @10psi	30	%	ASTM D575
t=1.0mm Percent Deflection % @50psi	56	%	ASTM D575
t=1.0mm Percent Deflection % @100psi	79	%	ASTM D575
Breakdown Voltage	14	KV/mm	ASTM D149
Volume Resistance	10 <sup>12</sup>	Ohm-cm	ASTM D257
Total Mass Loss	<0.4	%	ASTM E595
Tensile Strength	15	PSI	ASTM D412
Elongation	50	%	ASTM D412
Flammability Rating	V-0	-	UL 94
REACH/RoHS Compliant	Yes	-	REACH/RoHS

### TML TESTING REPORT 150°C 24h

Items	Unit	Testing Data							VC% = $\frac{A-B}{A} \times 100\%$
		No.1	No. 2	No.3	No. 4	No. 5	Average		
A	Before Baking	g	8.0238	8.0609	8.7119	8.5320	8.2350	-	
B	After Baking	g	8.0087	8.0466	8.6946	8.5151	8.2190	-	
VC	Volatile	%	0.19	0.18	0.20	0.20	0.19	0.19	